

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____

PRODUCT 产品: _____ SAW FILTER _____

MODEL NO 型号: _____ HDF395A-F11 _____

PREPARED 编制: _____ CHECKED 审核: _____

APPROVED 批准: _____ DATE 日期: _____ 2010-8-11 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. SCOPE

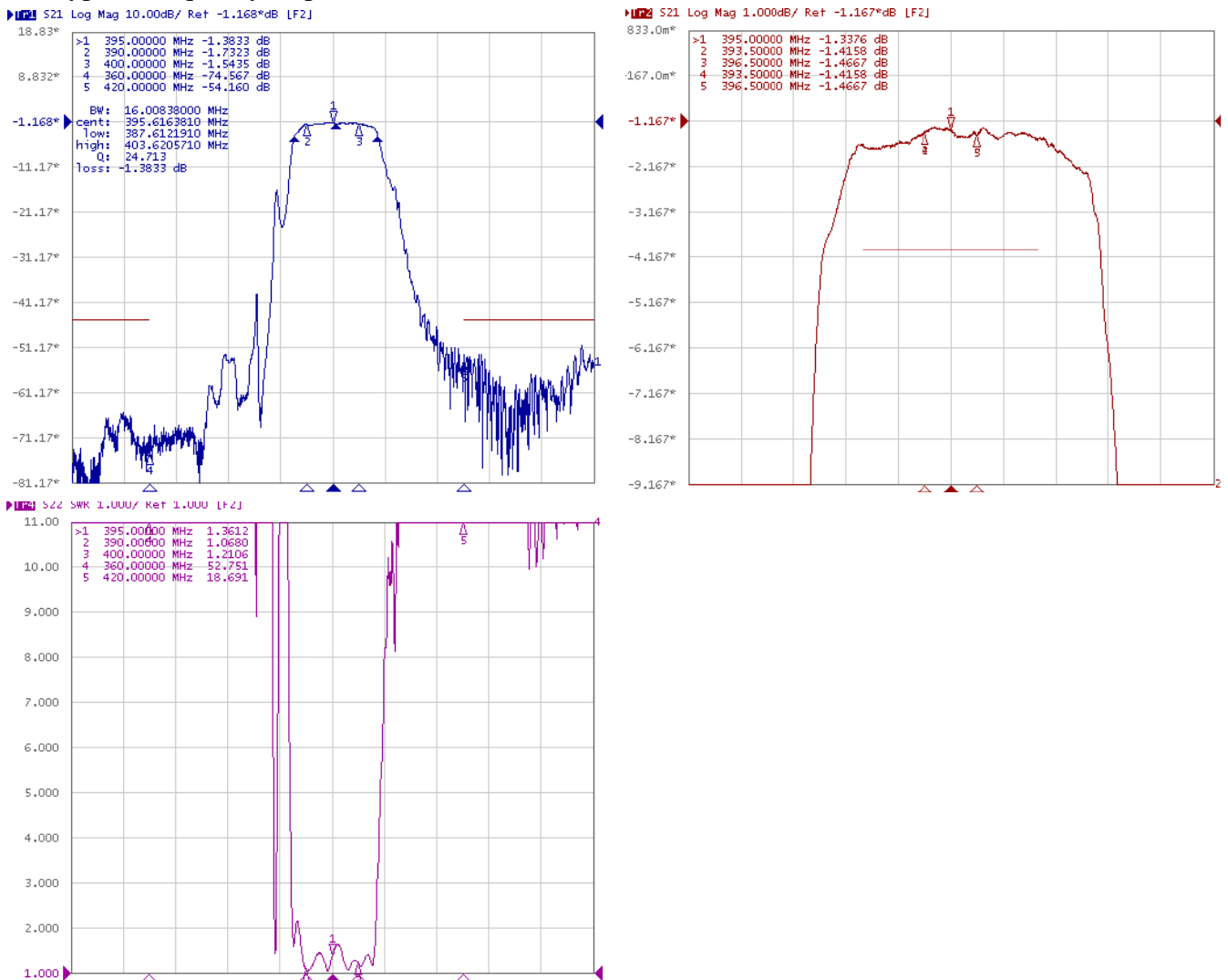
This specification shall cover the characteristics of SAW filter With F395A used for the page system.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

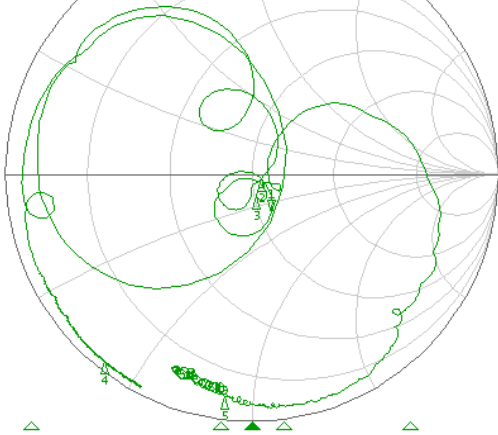
Electronic Characteristics

2-1. Typical frequency response



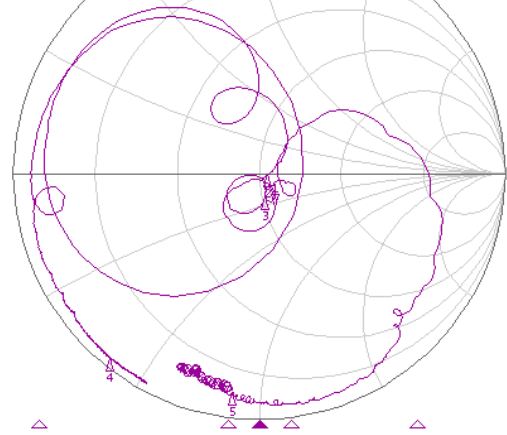
▶ **S11** Smith (R+jX) Scale 1.0000 [F2]

>1	395.00000 MHz	55.539 Ω	-17.908 Ω	22.500 pF
2	390.00000 MHz	53.895 Ω	-1.8109 Ω	225.35 pF
3	400.00000 MHz	51.227 Ω	-9.3309 Ω	42.642 pF
4	360.00000 MHz	1.0954 Ω	-24.155 Ω	16.302 pF
5	420.00000 MHz	4.4050 Ω	+44.165 Ω	8.5802 pF



▶ **S22** Smith (R+jX) Scale 1.0000 [F2]

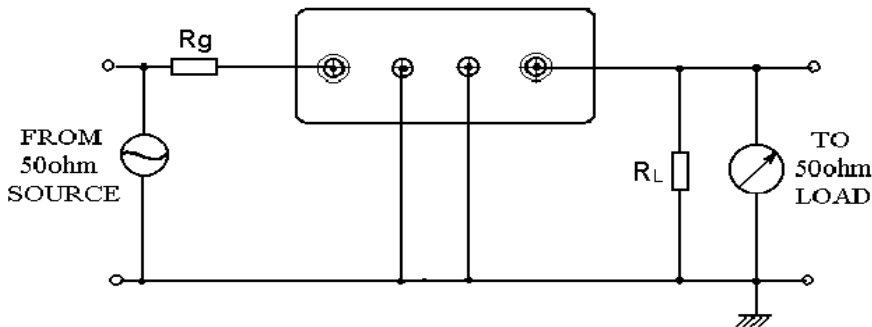
>1	395.00000 MHz	54.766 Ω	-15.457 Ω	26.067 pF
2	390.00000 MHz	53.354 Ω	-444.20 mΩ	918.71 pF
3	400.00000 MHz	51.478 Ω	-9.5945 Ω	41.470 pF
4	360.00000 MHz	1.1566 Ω	-23.867 Ω	18.524 pF
5	420.00000 MHz	4.7079 Ω	-43.861 Ω	8.6396 pF



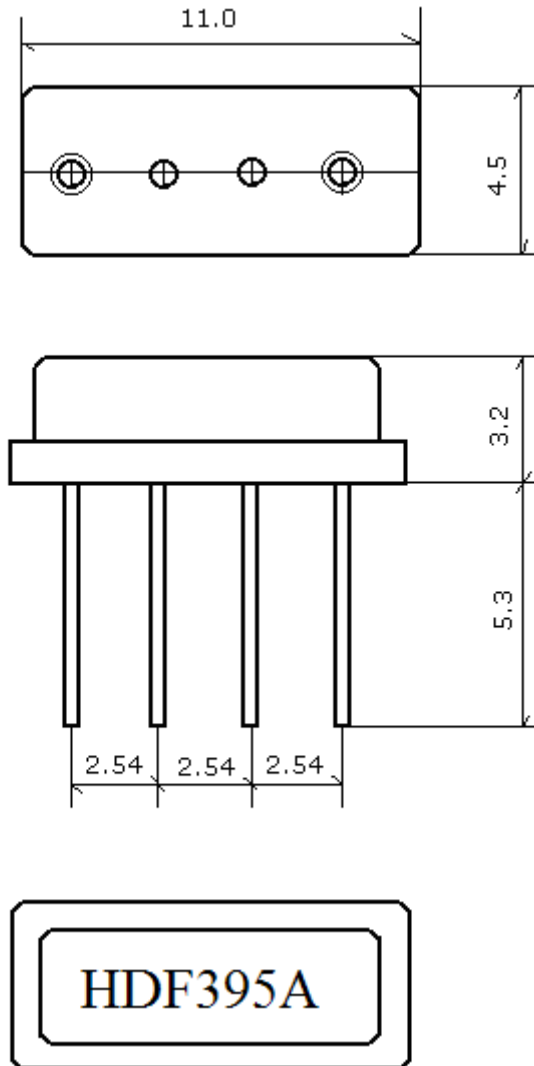
2-2.Electrical characteristics

Part number	F395A	Unit
Nominal center frequency (Fo)	395	MHz
Insertion Loss		dB
1.0.3MHz~fo-35 MHz	45min.	
2.fo ± 5.0 MHz	4.0max.	
3.fo +25MHz~ fo +45.8MHz	45min.	
Ripple (with Fo ± 5.0MHz)	2.0max	dB
Input/Output Impedance(Nominal)	50//0	Ω /pF

3. TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for

10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

5-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.